



Material Composition Sheet

Product: GS9023ACFYE3
 Package Type: LQFP-90/tray/Leadfree
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Die		28.07	Al	0.17	0.60	6056
			Si	27.90	99.39	993944
			Sub-total:	28.07	99.99	1000000
Die Attach		13.20	Ag	9.90	75.00	750000
			Epoxy Resin	3.30	25.00	250000
			Sub-total:	13.20	100.00	1000000
Lead Finish External		6.46	Sn	6.46	100.00	1000000
			Sub-total:	6.46	100.00	1000000
Leadframe		144.09	Cu	136.24	94.55	945520
			Fe	0.29	0.20	2013
			Mg	0.25	0.17	1735
			Mn	0.15	0.10	1041
			Ni	4.68	3.24	32480
			Si	1.04	0.72	7218
			Zn	1.44	0.99	9994
			Sub-total:	144.09	99.97	1000001
Marking Ink		0.01		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound		554.13	BrominatedEpoxyResin	5.20	0.93	9384
			Epoxy Resin	56.80	10.25	102503
			Phenol Resin	56.80	10.25	102503
			Sb302	5.20	0.93	9384
			SiO2	426.00	76.87	768773
			TBBA	4.13	0.74	7453
Sub-total:	554.13	99.97	1000000			
Wires	25 MGFLIB	2.62	Au	2.62	100.00	1000000
			Sub-total:	2.62	100.00	1000000
Total:		748.58				

GENNUM CORPORATION

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